This listing of claims will replace all prior versions, and listings, of claims in the application:

The Status of the Claims

1. (Previously amended) A method for fabricating an RF semiconductor device comprising:

forming a trench to define an active region and an element isolation region in a semiconductor substrate;

forming a plurality of gate lines within the active region of the semiconductor substrate, the plurality of gate lines not extending over a center of the trench;

forming an insulating layer on the plurality of gate lines and the semiconductor substrate;

forming at least one contact hole in the insulating layer within the active region without forming a contact hole within the element isolation region;

forming a contact plug in the contact hole; and

forming a conductive pattern layer that is electrically connected with the contact plug.

2. (Currently amended) A method as defined in claim 1, wherein the plurality of gate lines in the plurality are not connected with each other in the element isolation region.

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- 3. (Previously amended) A method as defined in claim 1, wherein at least two of the plurality of gate lines are connected in the active region.
- 4. (Original) A method as defined in claim 1, wherein a thickness of the insulating layer is about 1000 to about 20000 angstroms.
- 5. (Original) A method as defined in claim 1, wherein a thickness of the conductive pattern layer is above 10000 angstroms.
- 6. (Previously amended) A method as defined in claim 1, wherein the insulating layer is one of an oxide and a polyimide.
- 7. (Previously amended) A method as defined in claim 1, wherein the plurality of gate lines are formed in order to minimize parasitic capacitance between the plurality of gate lines and the substrate.
- 8. (Previously amended) A method as defined in claim 1, wherein the plurality of gate lines are formed in order to minimize resistance of the plurality of gate lines.
- 9. (Previously amended) A method as defined in claim 1, further comprising metal contacts linking at least two of the plurality of gate lines.

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10. (Previously amended) A method as defined in claim 1, wherein the plurality of gate lines do not extend along a longitudinal axis of the trench.

- 11. (Canceled)
- 12. (Canceled)
- 13. (Canceled)
- 14. (Canceled)